



SOT1347-1

plastic dual in-line package; 7 leads (300 mil)

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DIP8
Package type industry code	DIP7
Package style descriptive code	DIP (dual in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	076E03
JEDEC package outline code	MO-001
Mounting method type	T (through-hole mount)
Issue date	21-1-2013

Table 1. Package summary

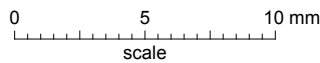
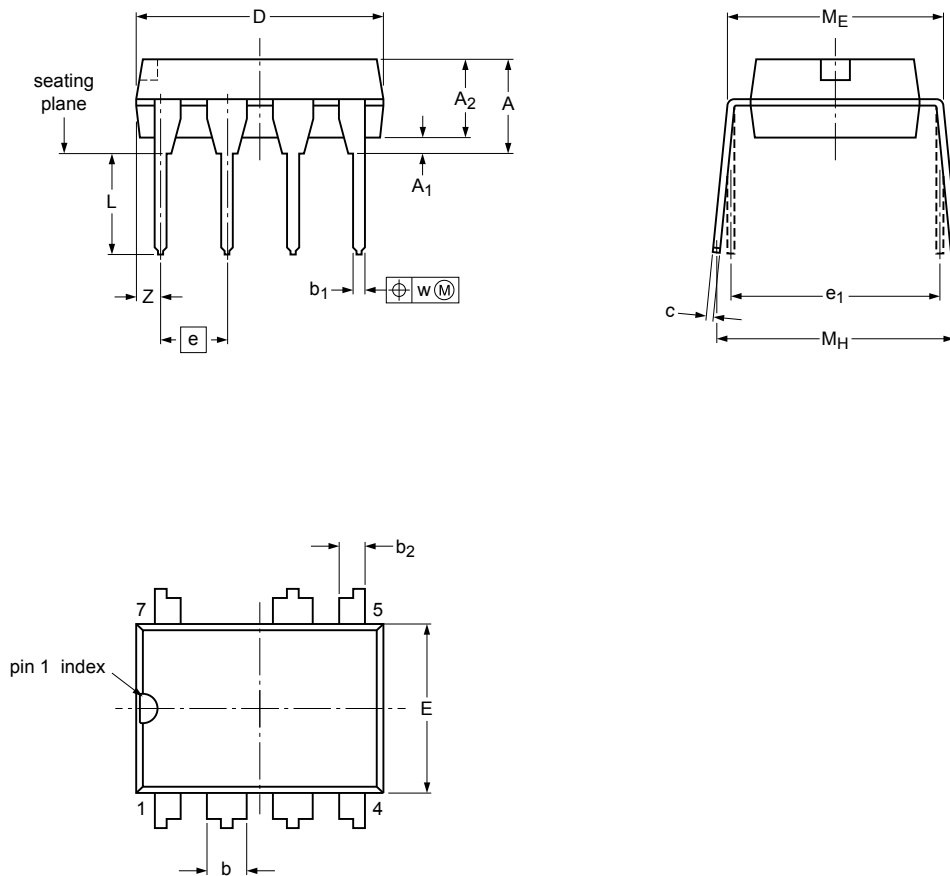
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.2	-	9.5	9.8	mm
E	package width	6.2	-	6.34	6.48	mm
A	seated height	[tbd]	-	[tbd]	4.2	mm
A ₂	package height	[tbd]	-	[tbd]	3.43	mm
e	nominal pitch	-	-	2.54	-	mm
n ₂	actual quantity of termination	-	-	7	-	



2. Package outline

DIP7: plastic dual in-line package; 7 leads (300 mil)

SOT1347-1



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	b ₁	b ₂	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	z ⁽¹⁾
max	4.2		3.43	1.73	0.53	1.07	0.38	9.8	6.48			3.60	7.88	9.40		
nom										2.54	7.62				0.254	1.15
min		0.51		1.14	0.38	0.89	0.20	9.2	6.20			3.05	7.62	7.88		

Note

1. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

sot1347-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1347-1	076E03	MO-001	---		-13-01-10- 13-01-21

Fig. 1. Package outline DIP7 (SOT1347-1)

3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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